

NOTES:

1. ALL DIMENSIONING AND TOLERANCES CONFORM TO ASME Y14.5-1994.
2. DATUM PLANE (E) LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD WIRE LEAD EXIT PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS (D) AND (D1) TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE (E).
4. DIMENSIONS (E1) AND (E2) INCLUDE MOLD PROTRUSION.
5. DIMENSIONS (D) AND (D1) PROTRUSION IS 0.054 MM PER SIDE.
6. DIMENSION (D) AND (D1) INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE (E).
7. (N) IS NUMBER OF TERMINALS.
8. PACKAGE TOP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS BY 0.10 MILLIMETERS AND TOP OF PACKAGE WILL NOT OVERHANG BOTTOM OF PACKAGE.
9. DIMENSIONS (b) DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION SHALL BE NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM (b) DIMENSION BY MORE THAN 0.08 MM. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
9. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 10. THE EXPOSED PAD IS COINCIDENT WITH THE TOP OR BOTTOM SURFACE OF THE PACKAGE AND NOT ALLOWED TO PROTRUDE BEYOND THAT SURFACE.
 - 11. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.20 MM FROM THE LEAD TIP.
 - 12. VAS DRAWING CONFORMS TO JEDEC REGISTERED OUTLINE MS-026-C, VARIATION B AND B1.
 - 13. BUT THE EXPOSED PAD DIMENSION WAS NOT SPECIFIED ON JEDEC.
 - 14. IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
 - 15. DIMENSION (E) AND (E2) SHOW THE MINIMUM CLEARANCE FOR THE EXPOSED PAD BE WHEN ALLOWED IS INSIDE OF LEAD FEET PINS IN ORDER NOT TO CONFLICT WITH THE LEAD CENERS. HOWEVER, THE SIZE OF THE EXPOSED PAD IS VARIABLE DEPENDING ON DEVICE FUNCTION (DIE SIZE).
 - 16. EXPOSED PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 0.05.
 - 17. CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 0.30 MM.

(JEDEC VARIATION)
ALL DIMENSIONS IN MILLIMETERS

SYMBOL	BFC			N	D	E
	MIN.	NDM.	MAX.			
A	~	~	1.20	13		
A1	0.05	0.10	0.15			
A2	0.95	1.00	1.05			
D	~	~	22.00 BSC.	4		
D1	~	~	20.00 BSC.			
D2	~	~	~	7.8		
E	~	~	22.00 BSC.	4		
E1	~	~	20.00 BSC.			
E2	2.00	~	~	7.8		
L	0.45	0.60	0.75	10, 14		
N	M129, 144					
e	~	~	0.50 BSC.	9		
b	0.17	0.22	0.27			
b1	0.17	0.20	0.23			
ccc	~	~	0.08			
ddd	~	~	0.08			

(JEDEC VARIATION)
ALL DIMENSIONS IN MILLIMETERS

SYMBOL	BFC			N	D	E
	MIN.	NDM.	MAX.			
A	~	~	1.20	13		
A1	0.05	0.10	0.15			
A2	0.95	1.00	1.05			
D	~	~	22.00 BSC.	4		
D1	~	~	20.00 BSC.			
D2	~	~	~	7.8		
E	~	~	22.00 BSC.	4		
E1	~	~	20.00 BSC.			
E2	2.00	~	~	7.8		
L	0.45	0.60	0.75	10, 14		
N	176 LD					
e	~	~	0.40 BSC.	9		
b	0.13	0.18	0.23			
b1	0.13	0.16	0.19			
ccc	~	~	0.08			
ddd	~	~	0.07			

* NOTE: THE 129 LEAD IS A COMPLIANT DEPOPULATION OF THE 144 LEAD MS-026 VARIATION BFA.

Amkor Technology, Inc.
 20000 Westborough, MA 01581
 Amkor Technology Philippines, Inc.
 1000/0/10 MM FORM (OPTIONAL, 6PAD)



PACKAGE OUTLINE, TOP, 20 X 20 MM BODY,
 1.00 mm THICK (OPTIONAL, 6PAD)
 35809
 PRINTING IS SCALED TO FIT
 DO NOT SCALE DRAWING
 1:1
 2 OF 2